

RECORDATION FORM COVER SHEET
PATENTS ONLY



103551214

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

2009.2.24

1. Name of conveying party(ies)
YuSik Kim
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Samsung Electronics Co., Ltd.
Internal Address: _____
Street Address: 416, Maetan-dong,
Yeongtong-gu
City: Suwon-si, Gyeonggi-do
State: _____
Country: Republic of Korea Zip: _____
Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):
Execution Date(s) January 7, 2009
 Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

4. Application or patent number(s):
A. Patent Application No.(s)
Additional numbers attached? Yes No

This document is being filed together with a new application.
B. Patent No.(s)
Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:
Name: Anthony P. Onello, Jr.
Internal Address: _____
Street Address: MILLS & ONELLO, LLP
Eleven Beacon Street, Suite 605
City: Boston
State: Massachusetts Zip: 02108
Phone Number: (617) 994-4900
Fax Number: (617) 742-7774
Email Address: mail@millsonello.com

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information
Deposit Account Number 50-1798
Authorized User Name Anthony P. Onello, Jr.

9. Signature: Anthony P. Onello, Jr. Signature
Anthony P. Onello, Jr.
Name of Person Signing

February 24, 2009 Date

Total number of pages including cover sheet, attachments, and documents: 3

ASSIGNMENT

I, YuSik Kim, of #101-1105, Dongsuwon LG village 1-cha APT, Mangpo-dong, Paldal-gu, Suwon-si, Gyeonggi-do, Republic of Korea, having invented improvements in LIGHT EMITTING DIODE PACKAGES, LIGHT EMITTING DIODE SYSTEMS AND METHODS OF MANUFACTURING THE SAME, described in an application for Letters Patent of the United States, executed by me on even date herewith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics, Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee my entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration I do also hereby sell, assign, and transfer unto the Assignee, all my rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and I do hereby authorize the Assignee to apply in my name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, I do hereby agree for myself and for my heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And I do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And I do hereby covenant for myself and my legal representatives and agree with the Assignee, that I have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions has not been otherwise encumbered by me, and that I have not executed and will not execute any instruments in conflict herewith.



Reference No.: SAM-1265

First or Sole Inventor:

Signature: 
YuSik Kim

Date: January 7, 2009

REFERENCE NO.: SAM-1265
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Page 2 of 2

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